



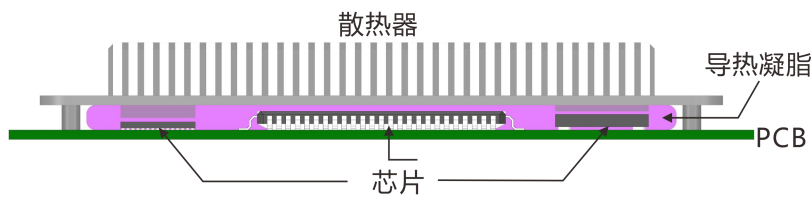
导热凝胶 Thermally Conductive Gel

1. 产品系列 Product Series: HTG-100、HTG-200、HTG-300、HTG-500

2. 产品描述 Description:

导热凝胶是单一组分、高适配性的热界面材料，该材料具有比超软导热硅胶垫片更优越的应力应变值，可自动点胶涂覆，是多个芯片共用一个散热器/结构件场合最佳的方案选择。

Thermally conductive gel is a creamy single-component and high suitability of the thermal interface material. The material has some stress-strain value lower than the softest silicone sheet. It can be automated dispensing and coating. It is the best solution that multiple chips share a radiator and structures occasion.



3. 产品特点

- 高导热性能，低热阻
- 杨氏模量小
- 无硅油析出，无污染
- 极佳的操作性

Features:

- High thermal conductivity, low thermal resistance
- Small Young modulus
- No oil and pollution
- Good machinability

4. 应用领域

- 半导体块和散热器
- 电源电阻器与底座之间
- 温度调节器与装配表面
- 热电冷却装置
- 高性能中央处理器及显卡处理器

Applications:

- Semiconductor cases and heat sink
- Power resistor and chassis
- Temperature regulator and Fabrications
- Thermoelectric cooling devices
- CPU's and GPU's

5. 贮藏条件及包装规格 Storage conditions and packaging specifications:

- 为确保产品维持良好质量，应将产品冷藏或低于 25℃ 之干燥环境中及密封之容器中。
In order to ensure that the products maintain the quality, it should be kept in low temperature with dry and sealed environment or container.
- 于储存期间，应确定密闭以外避免外来的污染影响电气特性。
During the storage period, make sure that the container is sealed to protect electrical performance from affecting by external contaminants.
- 包装规格：30cc/55cc/300cc
Packaging specifications: 30cc/55cc/300cc

6. 性能参数 Properties

序号 NO	项目 Items	技术指标 Value				测试方法 Test Method	
		HTG-100	HTG-200	HTG-300	HTG-500		
1	外观 Appearance	浅蓝色膏状物 Light blue pasty substance	浅绿色膏状物 Light green pasty substance	粉红色膏状物 Pink pasty substance	深灰色膏状物 Dark grey pasty substance	目视 Visual	
2	密度(g/cm ³) Density	2.4±0.5	2.8±0.5	3.2±0.5	3.1±0.5	ASTM D 792	
3	热阻(°C in ² /W)(@20psi) Thermal Resistance	≤0.25	≤0.12	≤0.08	≤0.04	ASTM D 5470	
4	挥发份 (200°C, 24h) ,ppm Volatilize point	≤300	≤200	≤200	≤200	GB269-85	
5	油离度 (200°C, 24h) ,% Solubility in water	≤0.3	≤0.2	≤0.2	≤0.2	SH/T0324-92	
6	导热系数(W/m·K) Thermal conductivity	1.0±0.2	2.0±0.2	3.0±0.25	5.0±0.5	ASTM D 5470	
7	体积电阻率(Ω·cm) Volume resistivity	≥1.0*10 ¹²	≥1.0*10 ¹²	≥1.0*10 ¹²	≥1.0*10 ¹⁰	ASTM D 257	
8	电压击穿强度(kV)(@1mm) Breakdown voltage	≥8	≥8	≥8	≥2.5	ASTM D 149	
9	50%瞬间压缩应力 (psi) 50%Instantaneous compressive stress	<10	<10	<10	<10	GB/T 7757-2009	
10	50%静态压缩应力 (psi) 50%Static compressive stress	<1	<1	<1	<1	GB/T 7757-2009	
11	粘接力 (psi) Adhesive force	<15	<15	<15	<15	--	
12	固化温度 (°C) Curing temperature	130	130	130	130	--	
13	固化时间 (min) Curing time	60	60	60	60	--	
14	使用温度 (°C) Temperature Range	-50~150	-50~150	-50~150	-50~150	--	
15	贮藏温度 (°C) Storage Temperature	25(6 mouths) 4(12 mouths)	25(6 mouths) 4(12 mouths)	25(6 mouths) 4(12 mouths)	25(6 mouths) 4(12 mouths)	--	
16	使用面积 (cm ² /g) Coverage Area Per Gram	@1 mil thickness	16	14	12.7	13	--
		@2mil thickness	8	7	6.35	6.5	
		@5 mil thickness	3.2	4.4	2.54	2.6	
		@10 mil thickness	1.6	1.4	1.27	1.3	

7. 环保要求 Environmental Request:

该系列产品符合 ROHS、卤素管控标准。

The series of products accord with standers of ROHS and HALOGEN.

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